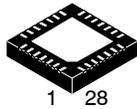


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

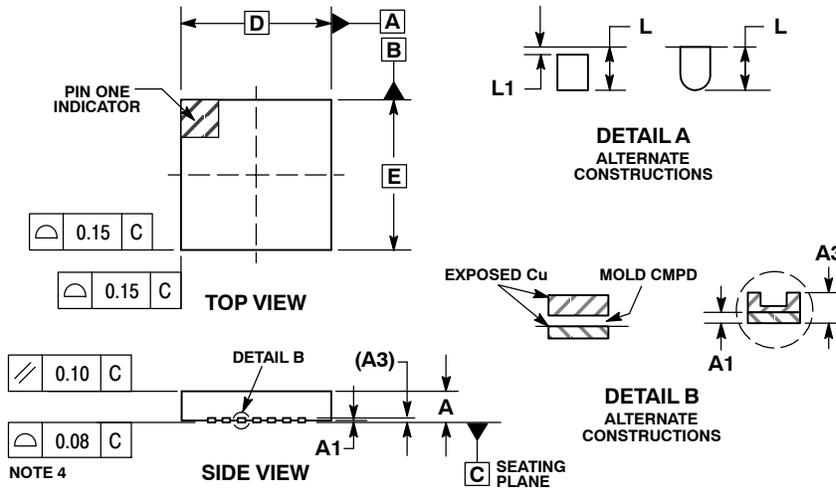
ON Semiconductor®



1 28
SCALE 2:1

QFN28 5x5, 0.5P
CASE 485BQ-01
ISSUE O

DATE 03 JAN 2011

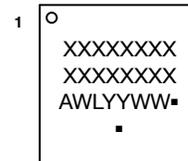


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25mm FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20	REF
b	0.20	0.30
D	5.00	BSC
D2	3.15	3.35
E	5.00	BSC
E2	3.15	3.35
e	0.50	BSC
K	0.32	REF
L	0.45	0.65
L1	0.05	0.15

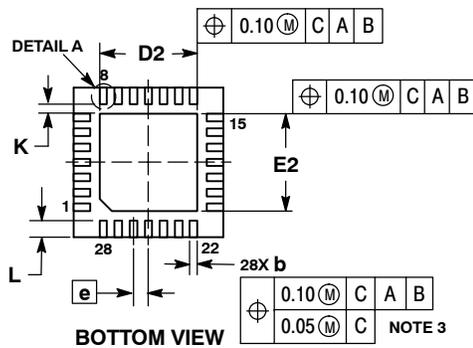
GENERIC MARKING DIAGRAM*



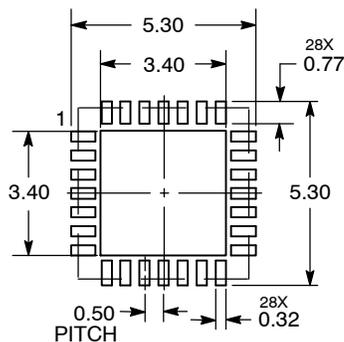
- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.



RECOMMENDED SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

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NEW STANDARD:		
DESCRIPTION:	QFN28, 5x5, 0.5P	PAGE 1 OF 2

